

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16419	
1.3 Title of PCN	Amkor ATJ (Japan) additional assembly line for STM32H74x & STM32H75x listed products in LQFP20x20 and LQFP14x14 packages	
1.4 Product Category	STM32H742x, STM32H743x, STM32H750 and STM32H753x.	
1.5 Issue date	2026-07-09	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Amkor ATJ (Japan)

4. Description of change

	Old	New
4.1 Description	Current assembly sites (depending on package): - ST Muar (Malaysia) Copper Alloy wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire, - AMKOR ATP (Philippine) Gold wire. - AMKOR ATP (Philippine) Copper Palladium wire. You may refer to 16419_Additional information.pdf document for further details.	Current assembly sites: (depending on package) : - ST Muar (Malaysia) Copper Alloy wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire, - AMKOR ATP (Philippine) Gold wire. - AMKOR ATP (Philippine) Copper Palladium wire. Additional assembly site for extended capacity: - Amkor ATJ (Japan) Copper Palladium wire .
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible on the marking Assembly Site code . - 99 : ST MUAR (Malaysia) - AA : ASE KaoHsiung (Taiwan) - 7B : AMKOR ATP (Philippines) - 6Z : AMKOR ATJ (Japan) Please refer to PCN 16419_Additional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-10-16
7.2 Intended start of delivery	2026-10-28

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
8.1 Description	16419 MDRF-GPAM-RER2517 PCN16419 ATJ3 LQFP14x14 to 20X20 CuPd wires STM32-reliability evaluation plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-07-09

9. Attachments (additional documentations)
16419 Public product.pdf 16419 MDRF-GPAM-RER2517 PCN16419 ATJ3 LQFP14x14 to 20X20 CuPd wires STM32- reliability evaluation plan.pdf 16419 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H743VIT6	
	STM32H743VIT6TR	
	STM32H750VBT6	
	STM32H750VBT6TR	

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